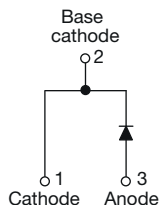


Fast Soft Recovery Rectifier Diode, 20 A



TO-220AC 2L



FEATURES

- Glass passivated pellet chip junction
- AEC-Q101 qualified
- Meets JESD 201 class 1A whisker test
- Flexible solution for reliable AC power rectification
- High surge, low V_F rugged blocking diode for DC charging stations
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	20 A
V_R	1200 V
V_F at I_F	1.31 V
I_{FSM}	320 A
t_{rr}	95 ns
T_J max.	150 °C
Snap factor	0.6
Package	TO-220AC 2L
Circuit configuration	Single

APPLICATIONS

- On-board and off-board EV/HEV battery chargers
- Input rectification

DESCRIPTION

The VS-20ETF12THM3 fast soft recovery rectifier series has been optimized for combined short reverse recovery time and low forward voltage drop.

The glass passivation ensures stable reliable operation in the most severe temperature and power cycling conditions.

MECHANICAL DATA

Case: TO-220AC 2L

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per J-STD-002

MAJOR RATINGS AND CHARACTERISTICS

SYMBOL	CHARACTERISTICS	VALUES	UNITS
V_{RRM}		1200	V
$I_{F(AV)}$	Sinusoidal waveform	20	A
I_{FSM}		320	
t_{rr}	1 A, 100 A/ μ s	95	ns
V_F	20 A, $T_J = 25$ °C	1.31	V
T_J	Range	-40 to +150	°C

VOLTAGE RATINGS

PART NUMBER	V_{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V	V_{RSM} , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	I_{RRM} AT 150 °C mA
VS-20ETF12THM3	1200	1300	6

ABSOLUTE MAXIMUM RATINGS

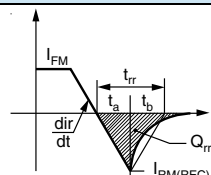
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum average forward current	$I_{F(AV)}$	$T_C = 113$ °C, 180° conduction half sine wave	20	A
Maximum peak one cycle non-repetitive surge current	I_{FSM}	10 ms sine pulse, rated V_{RRM} applied	270	
		10 ms sine pulse, no voltage reapplied	320	
Maximum I^2t for fusing	I^2t	10 ms sine pulse, rated V_{RRM} applied	365	A ² s
		10 ms sine pulse, no voltage reapplied	515	
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	$t = 0.1$ ms to 10 ms, no voltage reapplied	5150	A ² $\sqrt{s}$

ELECTRICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum forward voltage drop	V_{FM}	20 A, $T_J = 25\text{ }^{\circ}\text{C}$	1.31	V
Forward slope resistance	r_t	$T_J = 150\text{ }^{\circ}\text{C}$	11.88	m Ω
Threshold voltage	$V_{F(TO)}$		0.93	V
Maximum reverse leakage current	I_{RM}	$T_J = 25\text{ }^{\circ}\text{C}$	0.1	mA
		$T_J = 150\text{ }^{\circ}\text{C}$	6	

 $V_R = \text{rated } V_{RRM}$
RECOVERY CHARACTERISTICS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Reverse recovery time	t_{rr}	I_F at 20 A _{pk} 25 A/ μ s 25 $^{\circ}\text{C}$	400	ns
Reverse recovery current	I_{rr}		6.1	A
Reverse recovery charge	Q_{rr}		1.7	μ C
Snap factor	S	Typical	0.6	


THERMAL - MECHANICAL SPECIFICATIONS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum junction and storage temperature range	T _J , T _{Stg}		-40 to +150	°C
Maximum thermal resistance, junction to case	R _{thJC}	DC operation	0.9	°C/W
Maximum thermal resistance, junction to ambient	R _{thJA}		62	
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, smooth and greased	0.5	
Approximate weight			2	g
			0.07	oz.
Mounting torque	minimum		6 (5)	kgf · cm (lbf · in)
	maximum		12 (10)	
Marking device		Case style TO-220AC 2L	20ETF12TH	

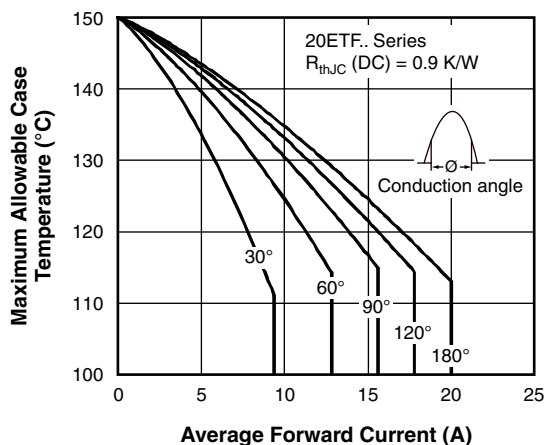


Fig. 1 - Current Rating Characteristics

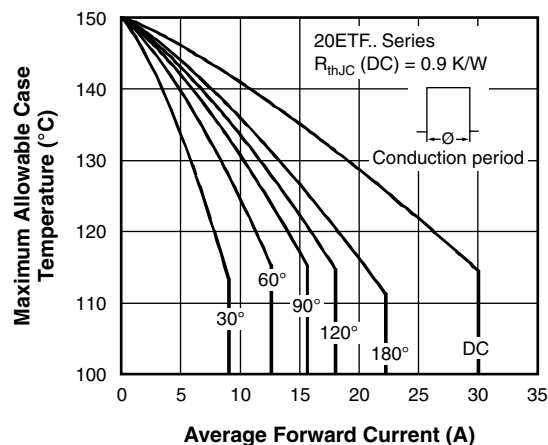


Fig. 2 - Current Rating Characteristics

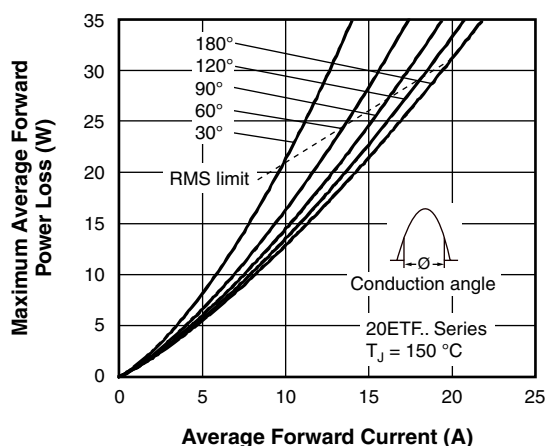


Fig. 3 - Forward Power Loss Characteristics

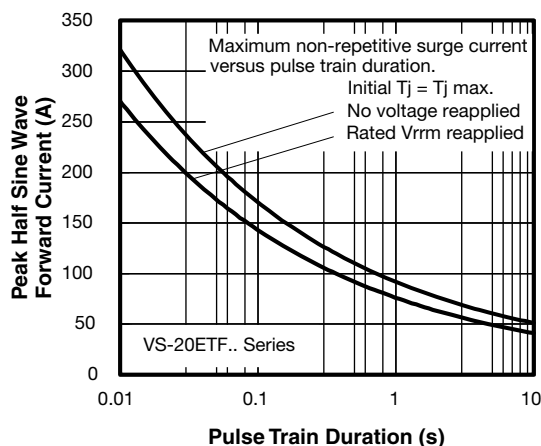


Fig. 6 - Maximum Non-Repetitive Surge Current

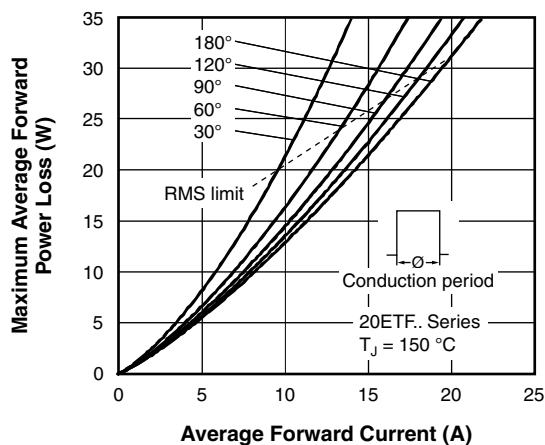


Fig. 4 - Forward Power Loss Characteristics

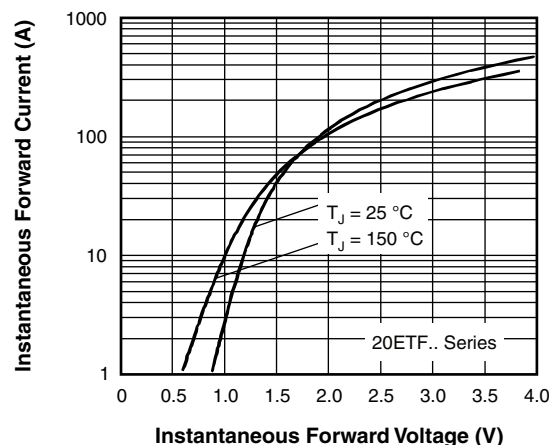


Fig. 7 - Forward Voltage Drop Characteristics

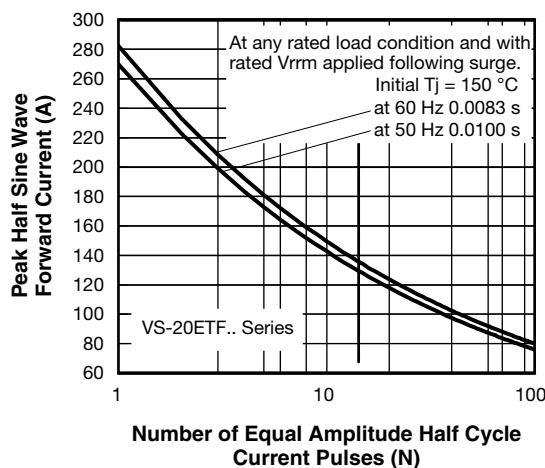
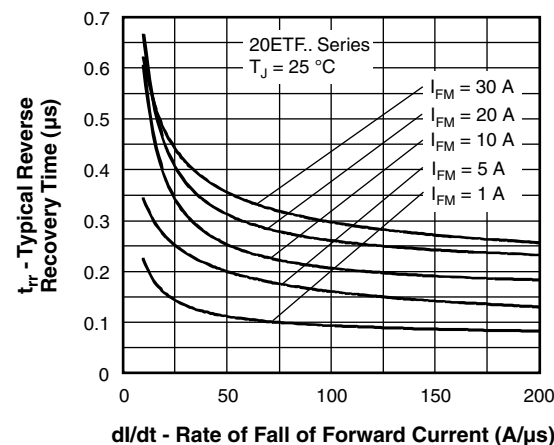
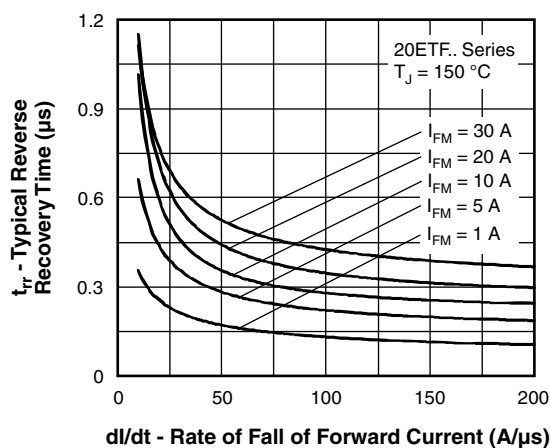
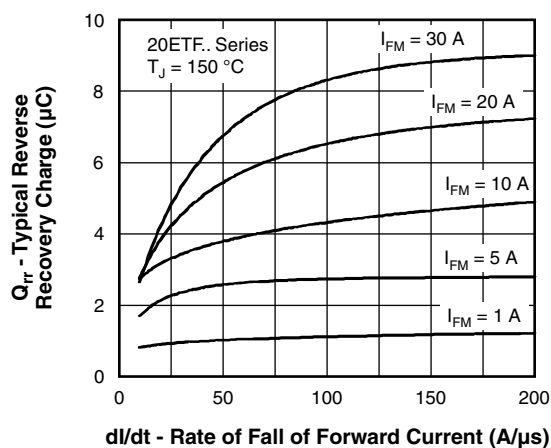
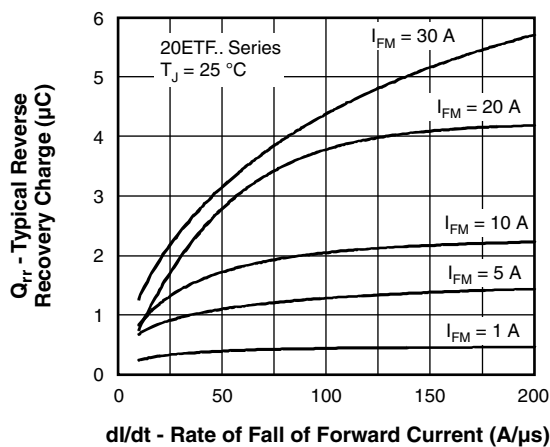
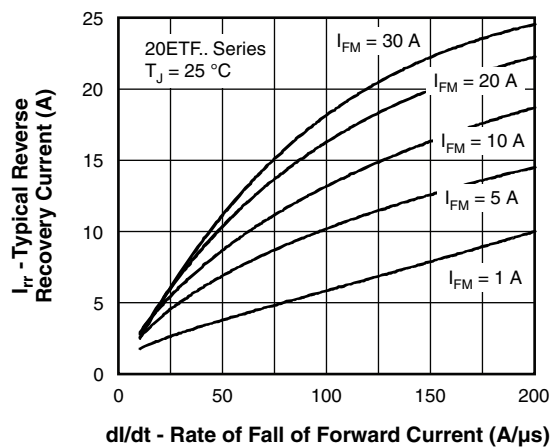
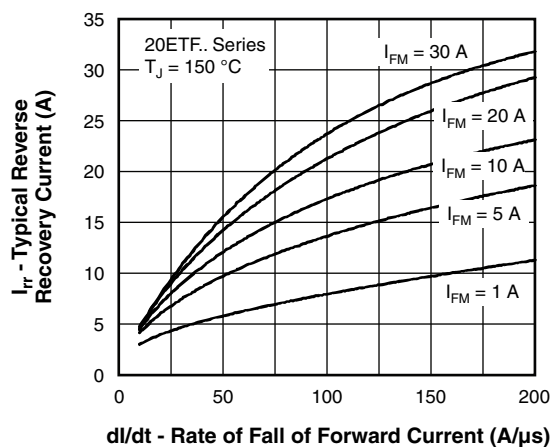
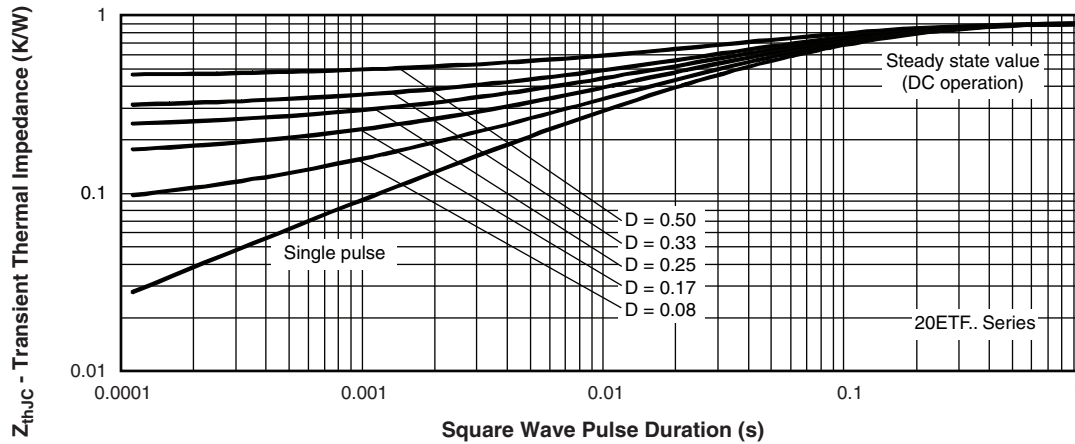


Fig. 5 - Maximum Non-Repetitive Surge Current


Fig. 8 - Recovery Time Characteristics, $T_J = 25\text{ }^{\circ}\text{C}$


Fig. 9 - Recovery Time Characteristics, $T_J = 150^\circ C$

Fig. 11 - Recovery Charge Characteristics, $T_J = 150^\circ C$

Fig. 10 - Recovery Charge Characteristics, $T_J = 25^\circ C$

Fig. 12 - Recovery Current Characteristics, $T_J = 25^\circ C$

Fig. 13 - Recovery Current Characteristics, $T_J = 150^\circ C$


Fig. 14 - Thermal Impedance Z_{thJC} Characteristics

ORDERING INFORMATION TABLE

Device code	VS-	20	E	T	F	12	T	H	M3
	1	2	3	4	5	6	7	8	9
1	Vishay Semiconductors product								
2	Current rating (20 = 20 A)								
3	Circuit configuration: E = TO-220AC 2L A = TO-220AB 3L, common anode								
4	Package: T = TO-220								
5	Type of silicon: S = standard recovery rectifier								
6	Voltage code x 100 = V_{RRM} ——— 12 = 1200 V								
7	- None = TO-220AB - T = True pin TO-220								
8	H = AEC-Q101 qualified								
9	Environmental digit: M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free								

ORDERING INFORMATION (Example)

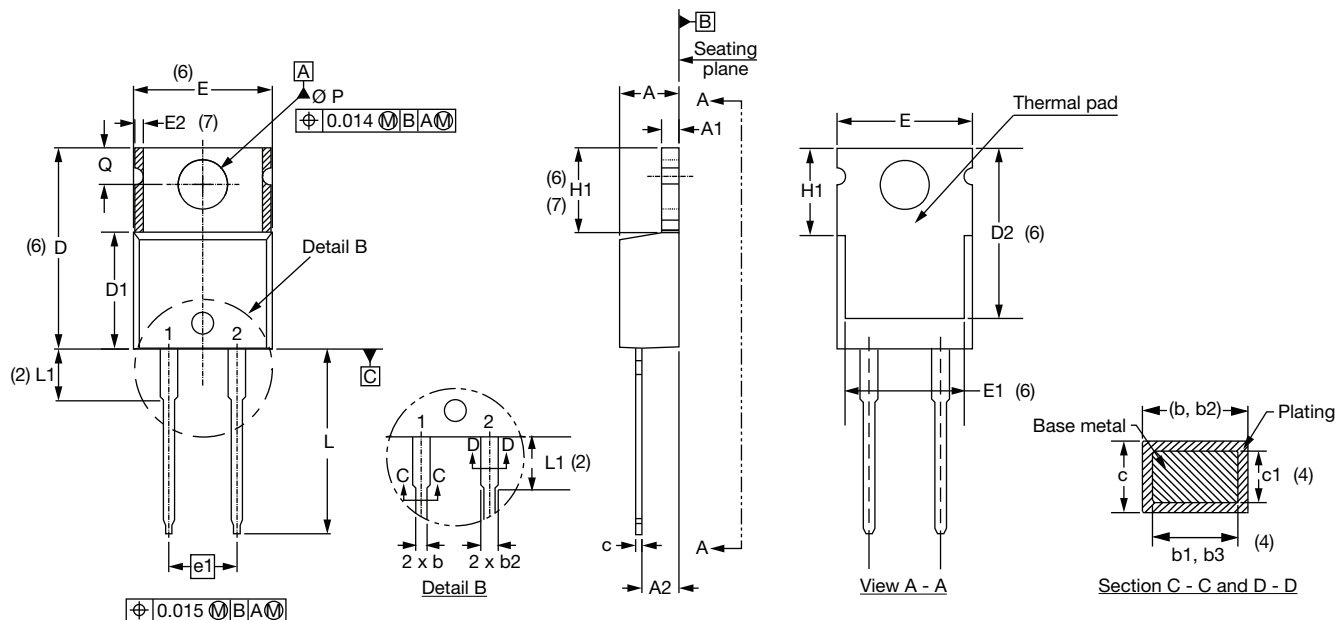
PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-20ETF12THM3	50	1000	Antistatic plastic tube

LINKS TO RELATED DOCUMENTS

Dimensions	www.vishay.com/doc?96069
Part marking information	www.vishay.com/doc?95391
SPICE model	www.vishay.com/doc?96866

TO-220AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.56	2.92	0.101	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
c	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.25	0.585	0.600	3
D1	8.38	9.02	0.330	0.355	
D2	11.68	12.88	0.460	0.507	6
E	10.11	10.51	0.398	0.414	3, 6

Notes

- (1) Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1 and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3 and c1 apply to base metal only
- (5) Controlling dimension: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2 and E1
- (7) Dimension E2 x H1 define a zone where stamping and singulation irregularities are allowed
- (8) Outline conforms to JEDEC® TO-220, except D2, where JEDEC® minimum is 0.480"



Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Hyperlinks included in this datasheet may direct users to third-party websites. These links are provided as a convenience and for informational purposes only. Inclusion of these hyperlinks does not constitute an endorsement or an approval by Vishay of any of the products, services or opinions of the corporation, organization or individual associated with the third-party website. Vishay disclaims any and all liability and bears no responsibility for the accuracy, legality or content of the third-party website or for that of subsequent links.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.